

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|-----------------|----------------|--|------------|-----------------|-------------------------|------------------|
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.45794 | 100.0 | 6.6 |
| Subtotal | | | | 0.45794 | 100 | 6.6 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01035 | 100.0 | 0.1491 |
| | Pure metal | Aluminium (Al) | 7429-90-5 | 0.15611 | 100.0 | 2.25 |
| Subtotal | | | | 0.16646 | 200 | 2.3991 |
| Post-plating | Pure Metal | Tin (Sn) | 7440-31-5 | 1.73461 | 100.0 | 25 |
| Subtotal | | | | 1.73461 | 100 | 25 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.02331 | 0.04 | 0.336 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.05828 | 0.1 | 0.84 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 58.20118 | 99.86 | 838.824 |
| Subtotal | | | | 58.28277 | 100 | 840 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 3.39549 | 8.7 | 48.9375 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 6.24458 | 16.0 | 90 |
| | Filler | Silica fused | 60676-86-0 | 29.27148 | 75.0 | 421.875 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.11709 | 0.3 | 1.6875 |
| Subtotal | | | | 39.02864 | 100 | 562.5 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.01648 | 5.0 | 0.2375 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.00824 | 2.5 | 0.11875 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.30486 | 92.5 | 4.39375 |
| Subtotal | | | | 0.32958 | 100 | 4.75 |
| Total | | | | 100 | 100 | 1441.2491 |

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